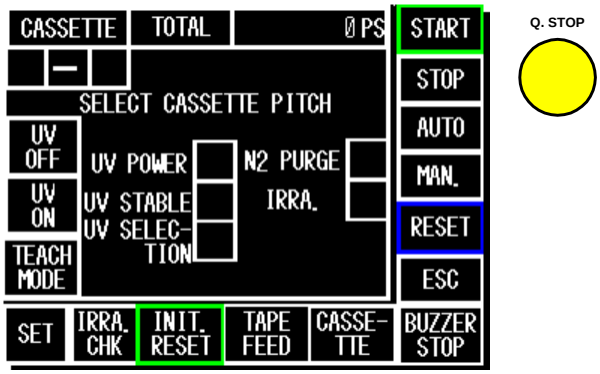
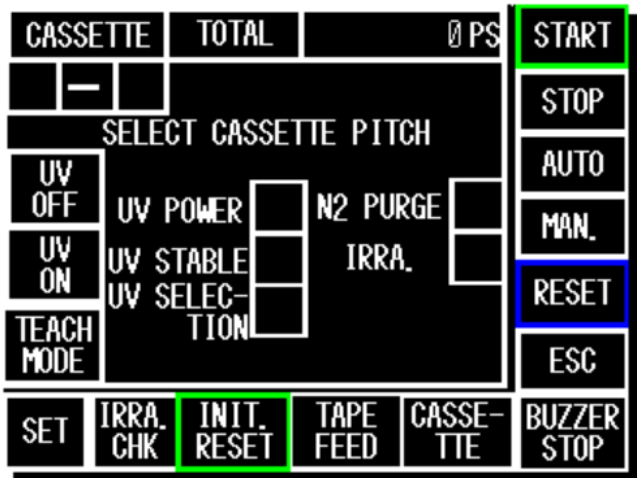
8.10 Robot teaching for press down plate

Perform 8.2 Preparation for robot teaching before starting the procedure shown below.
Do not change T(Theta-axis) and R(R-axis) data for correct operation.



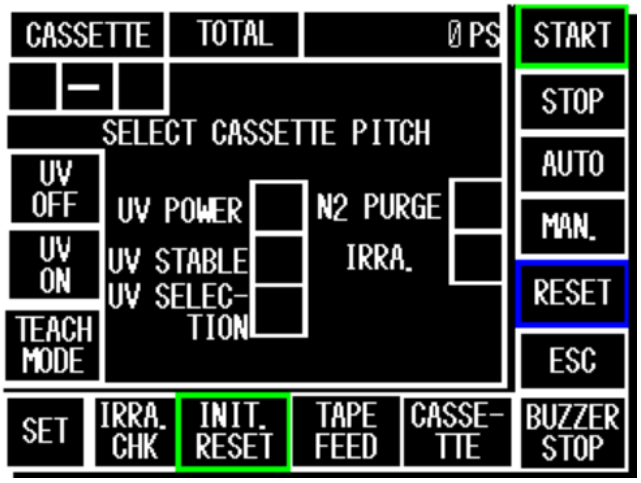
(1) Press [Q. STOP] key.



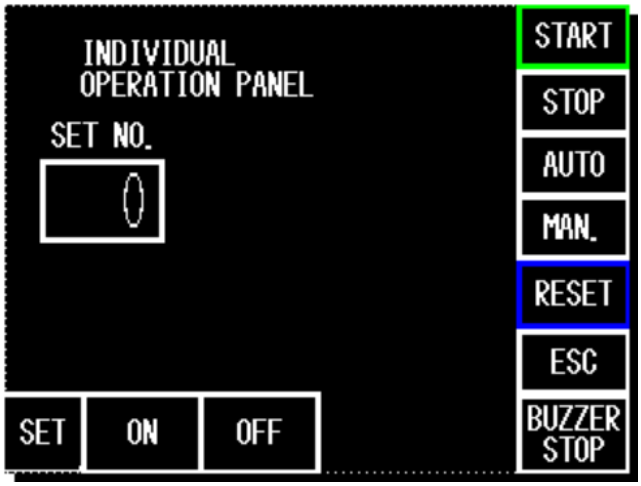
(2) Press [BUZZER STOP] key on MAIN SCREEN.

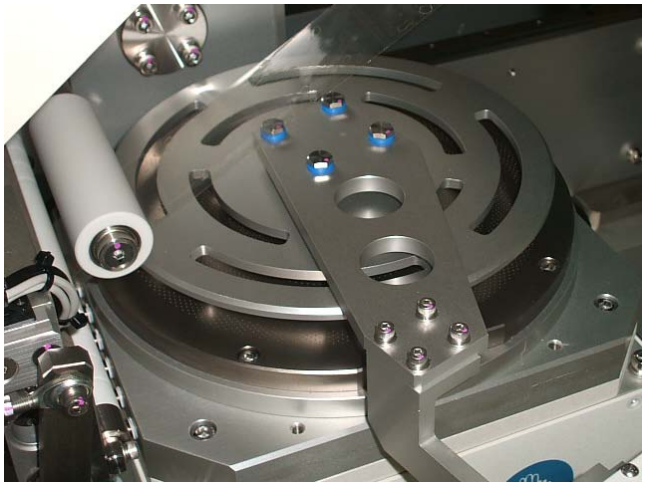
(3) Connect the teach pendant with the machine, and press [TEACH MODE] key on the MAINSCREEN.

(4) Press [MAINTENANCE] key on the teach pendant. “RANDOM” is displayed on the teach pendant screen.
Press [BUZZER STOP] key on MAIN SCREEN.



(5) Press [SET] key on the MAIN SCREEN. "INDIVIDUAL OPERATION PANEL" is displayed.

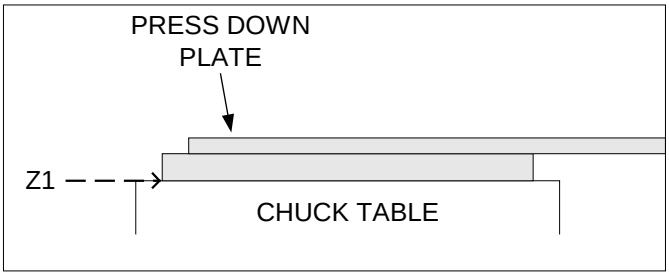




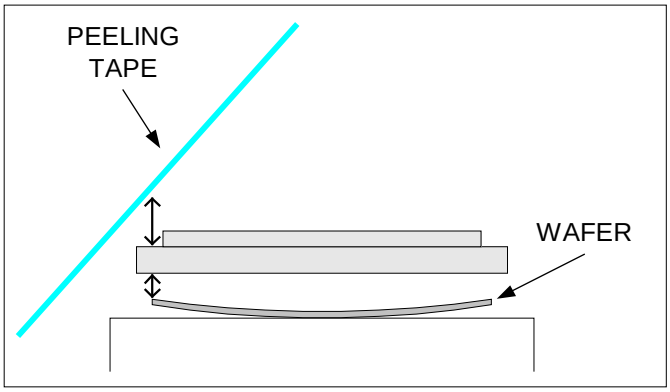
(6) Rotate the robot arm with teach pendant. T=1100, Z=1500

(7) Press the display of "INDIVIDUAL OPERATION PANEL". The keyboard is displayed. Enter "762" (Press down plate forward), and press [ON] key.

(8) Fine adjust the T-axis position so that the press down plate position is at the same position as the wafer chuck area.



(9) Moves the press down plate downward until it contacts the chuck table. (R-axis) The value of Z at the position is **Z_1**.



(10) Moves the press down plate upward. (R-axis)
Place the wafer having warpage (maximum warpage in your wafer) on the chuck table.

(11) Adjust the pressdown plate position so that it does not contact both peeling tape and wafer warpage. The value of Z at the position is **Z_2**.

Stroke = Z_2 - Z_1
Offset = 100 (Fixed)
Z = Z_2 – Offset

(12) After positioning, press [READ POSITION] key. The current position of Z is displayed. To save the value, press [TEMP] key holding down [SHIFT] key.